

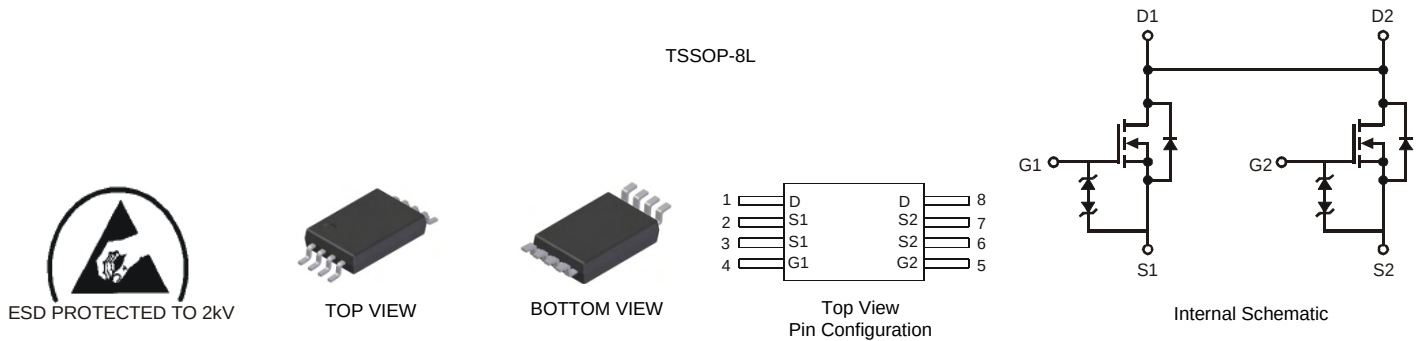
Features

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- **Lead Free By Design/RoHS Compliant (Note 1)**
- **ESD Protected Up To 2KV**
- **"Green" Device (Note 2)**
- **Qualified to AEC-Q101 Standards for High Reliability**

Mechanical Data

- Case: TSSOP-8L
- Case Material: Molded Plastic, "Green" Molding Compound.
UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram Below
- Marking Information: See Page 4
- Ordering Information: See Page 4
- Weight: 0.039 grams (approximate)

NEW PRODUCT



Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V _{DSS}	20	V
Gate-Source Voltage			V _{GSS}	±8	V
Continuous Drain Current (Note 3)	Steady State	T _A = 25°C	I _D	8.58	A
		T _A = 85°C		5.73	
Pulsed Drain Current (Note 4)			I _{DM}	36	A

Thermal Characteristics

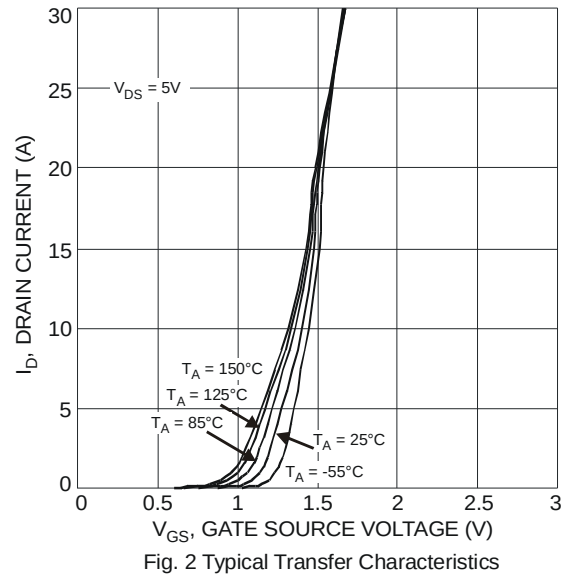
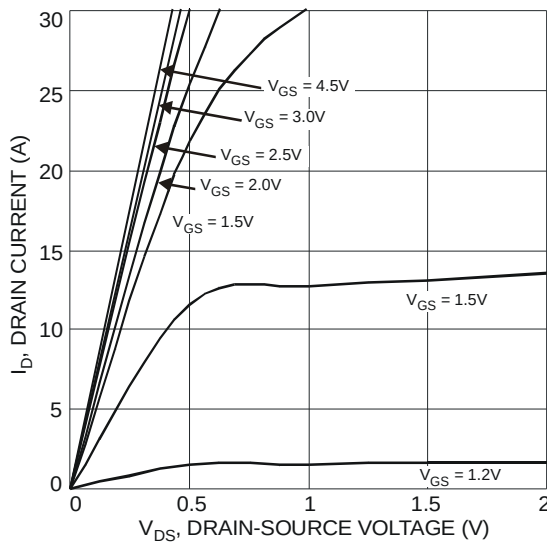
Characteristic	Symbol	Value	Unit
Power Dissipation (Note 3)	P _D	0.88	W
Thermal Resistance, Junction to Ambient @T _A = 25°C (Note 3)	R _{θJA}	141.57	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

- Notes:
1. No purposefully added lead.
 2. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.
 3. Device mounted on FR-4 PCB, with minimum recommended pad layout.
 4. Repetitive rating, pulse width limited by junction temperature.

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 5)						
Drain-Source Breakdown Voltage	BV _{DSS}	20	-	-	V	V _{GS} = 0V, I _D = 250μA
Zero Gate Voltage Drain Current T _J = 25°C	I _{DSS}	-	-	1.0	μA	V _{DS} = 20V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	-	-	±10	μA	V _{GS} = ±8V, V _{DS} = 0V
ON CHARACTERISTICS (Note 5)						
Gate Threshold Voltage	V _{GS(th)}	0.4	0.72	1.0	V	V _{DS} = V _{GS} , I _D = 250μA
Static Drain-Source On-Resistance	R _{DS(on)}	-	11	14.5	mΩ	V _{GS} = 4.5V, I _D = 9.4A
			13	16.5		V _{GS} = 2.5V, I _D = 8.3A
Forward Transfer Admittance	Y _{fs}	-	19	-	S	V _{DS} = 5V, I _D = 9.4A
Diode Forward Voltage	V _{SD}	-	0.65	1.2	V	V _{GS} = 0V, I _S = 1.3A
DYNAMIC CHARACTERISTICS (Note 6)						
Input Capacitance	C _{iss}	-	1495	-	pF	V _{DS} = 10V, V _{GS} = 0V, f = 1.0MHz
Output Capacitance	C _{oss}	-	161	-	pF	
Reverse Transfer Capacitance	C _{rss}	-	152	-	pF	
Gate Resistance	R _g	-	1.42	-	Ω	V _{DS} = 0V, V _{GS} = 0V, f = 1MHz
Total Gate Charge	Q _g	-	16.5	-	nC	V _{GS} = 4.5V, V _{DS} = 10V, I _D = 9.4A
Gate-Source Charge	Q _{gs}	-	2.5	-	nC	
Gate-Drain Charge	Q _{gd}	-	3.2	-	nC	
Turn-On Delay Time	t _{D(on)}	-	10.39	-	ns	V _{DD} = 10V, V _{GS} = 4.5V, R _{GEN} = 6Ω, I _D = 1A, R _L = 10Ω
Turn-On Rise Time	t _r	-	11.66	-	ns	
Turn-Off Delay Time	t _{D(off)}	-	59.38	-	ns	
Turn-Off Fall Time	t _f	-	16.27	-	ns	

- Notes: 5. Short duration pulse test used to minimize self-heating effect.
6. Guaranteed by design. Not subject to production testing.



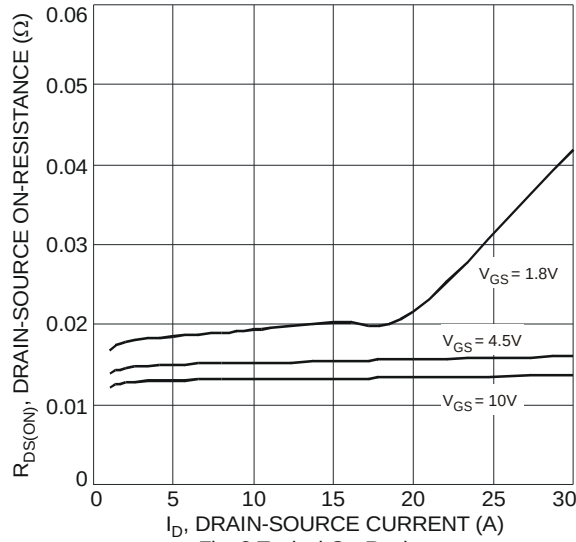


Fig. 3 Typical On-Resistance vs. Drain Current and Gate Voltage

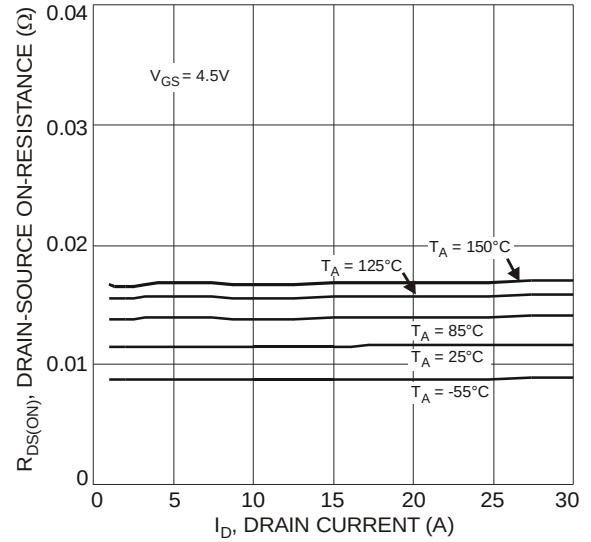


Fig. 4 Typical Drain-Source On-Resistance vs. Drain Current and Temperature

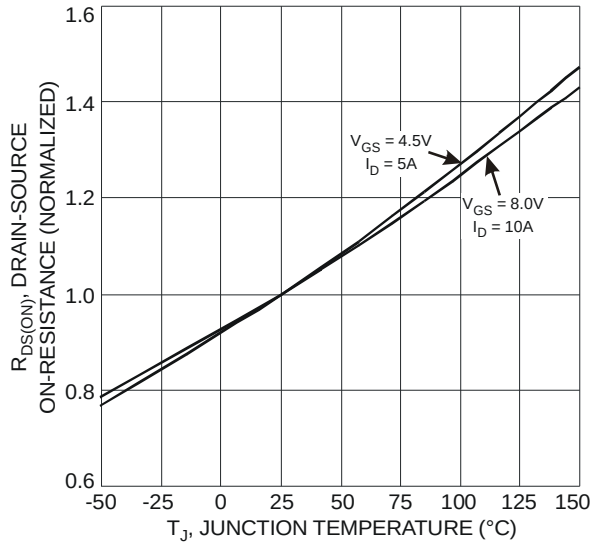


Fig. 5 On-Resistance Variation with Temperature

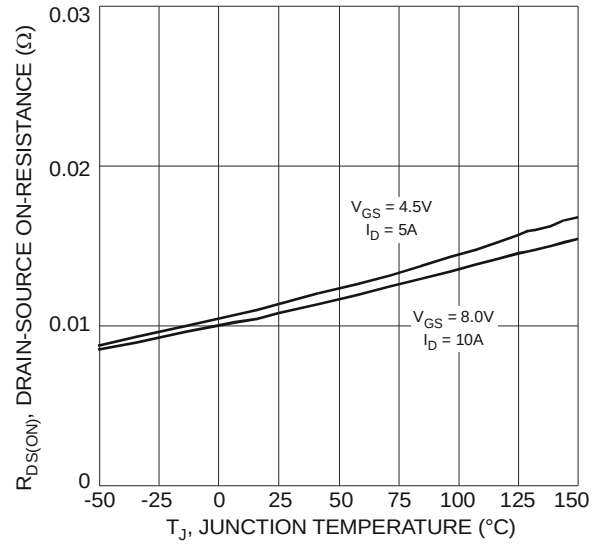


Fig. 6 On-Resistance Variation with Temperature

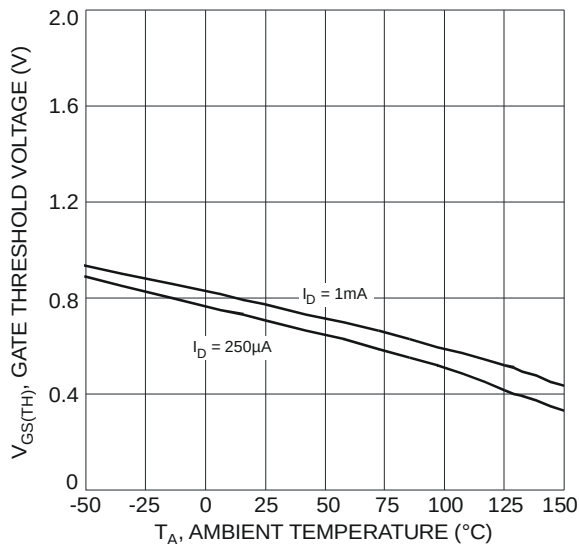


Fig. 7 Gate Threshold Variation vs. Ambient Temperature

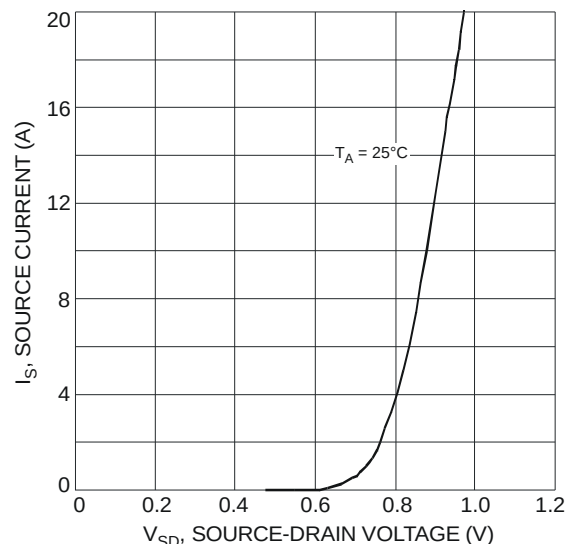
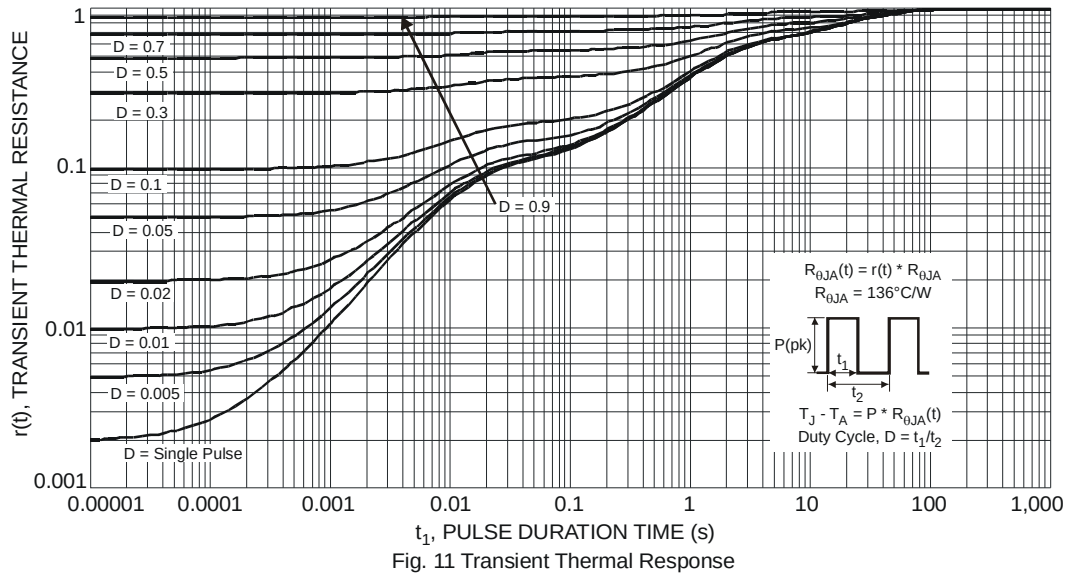
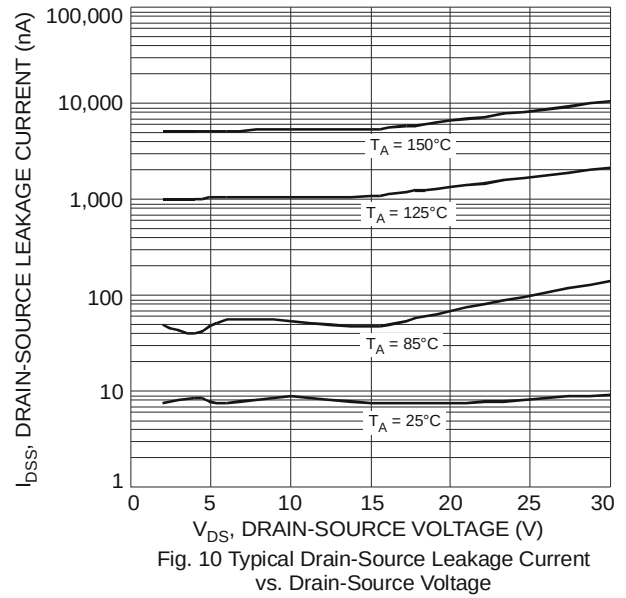
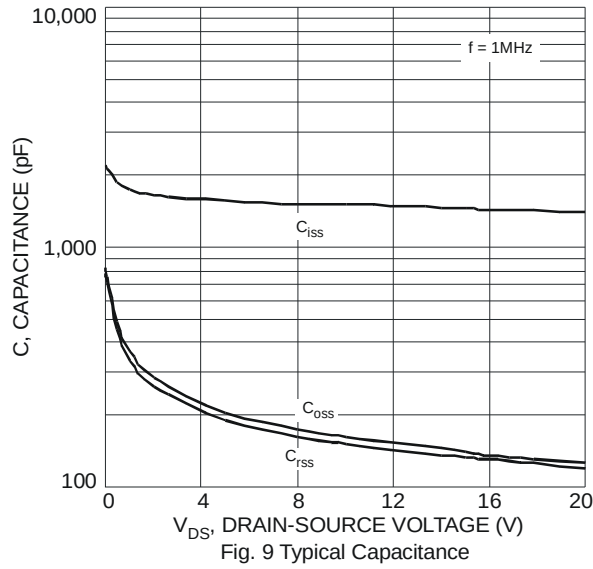


Fig. 8 Diode Forward Voltage vs. Current

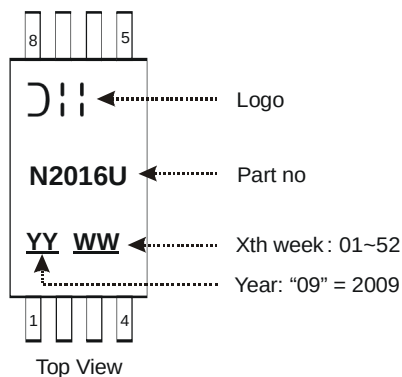


Ordering Information (Note 7)

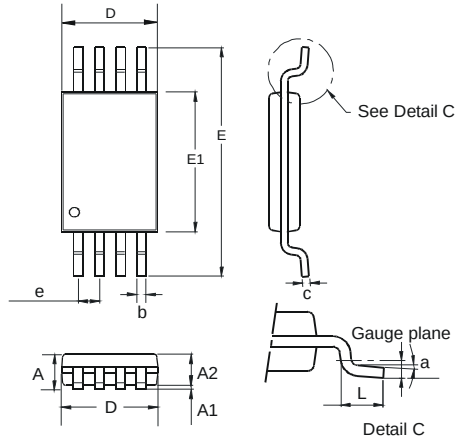
Part Number	Case	Packaging
DMN2016UTS-13	TSSOP-8L	2500 / Tape & Reel

Notes: 7. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

Marking Information

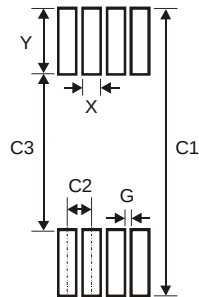


Package Outline Dimensions



TSSOP-8L			
Dim	Min	Max	Typ
a	0.09	—	—
A	—	1.20	—
A1	0.05	0.15	—
A2	0.825	1.025	0.925
b	0.19	0.30	—
c	0.09	0.20	—
D	2.90	3.10	3.025
e	—	—	0.65
E	—	—	6.40
E1	4.30	4.50	4.425
L	0.45	0.75	0.60
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
X	0.45
Y	1.78
C1	7.72
C2	0.65
C3	4.16
G	0.20

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